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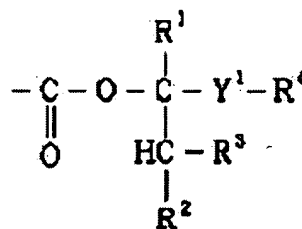
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## (54) HYDROGENATED POLYBUTADIENE MODIFIED POLYMER CONTAINING EPOXY GROUP AND SOFT THERMOSETTING RESIN COMPOSITION CONTAINING IT

(57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain a composition having excellent storage stability, electric insulation property, adhesiveness, chemical resistance and softness by blending a hydrogenated polybutadiene modified polymer (A) containing an epoxy group and a compound (B) having a carboxyl group which is blocked with either a vinyl (thio)ether or a heterocyclic compound having a vinyl type double bond.

**SOLUTION:** The component A has (a) a part consisting of a hydrogenated polybutadiene resin having a number average molecular weight of 500-10,000 and a resin acid value of 10-250 mgKOH/g and (b) a part consisting of a polymer of a vinyl monomer having an epoxy group. These two parts are reacted and bonded such that the equivalent ratio of the carboxyl group of the content (a) against the epoxy group of the content (b) be not more than 0.2. The obtained product is a modified polymer having an epoxy equivalent 200-2,000 g/mol. the component B is a compound having at least two functional groups of the formula (wherein R1-R3 are each H or a 1-18C organic group; R4 is a 1-18C organic group; and Y' is O or S) per a molecule.



### LEGAL STATUS

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